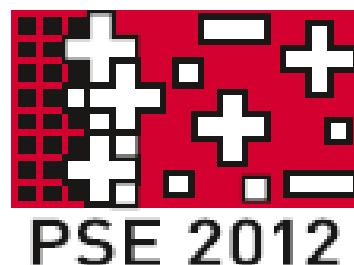


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**Electrical and optical properties of AlN<sub>x</sub>O<sub>y</sub> thin films deposited by reactive DC magnetron sputtering**

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Aluminium, Al, is a metallic material used in a large variety of technological fields, such as surface plasmon-coupled emission (SPCE) devices for biochemical applications and it is also a good candidate to be used as nonresonant plasmonic nanoparticle in thin-film silicon solar cells. Aluminium nitride, AlN, is a semiconductor material and it can be used in the fabrication of optical sensors, LEDs, surface/bulk acoustic wave devices and in electronic packaging. Aluminium oxide, Al<sub>2</sub>O<sub>3</sub>, is an insulator material, used as protective film, as gate dielectric in flash memory circuits, OTFTs, MOSFET, etc. The AlO<sub>y</sub> system is also important in solar selective coatings since it exhibits very high solar selectivity. The possibility to associate the overall set of properties of the above mentioned base-materials might be the starting point for a material that may combine specific advantages of each of the three systems, Al, AlN<sub>x</sub> and AlO<sub>y</sub>, according to the particular requirements of a given application. In fact, the addition of small amounts of oxygen and nitrogen to a growing Al film can give rise to an oxynitride film with a wide range of different properties, where the optical and electrical ones may be tailored between those of the pure aluminium and those of aluminum nitride and oxide. In this work thin films of AlN<sub>x</sub>O<sub>y</sub> were prepared by reactive DC magnetron sputtering, using a pure Al target and an Ar/(N<sub>2</sub>,O<sub>2</sub>) gas mixture. Preliminary Transmission Electron Microscopy and EELS analysis suggested the growth of films with Al nanoparticles randomly embedded in an AlN<sub>x</sub>O<sub>y</sub> matrix. The particular structure, morphology and composition of the films induced a wide variation in the electrical properties, which can be explained using a tunnel barrier conduction mechanism for the electric charge transport through the films, as well as distinct optical responses, such as an unusual large broadband absorption for some films, with potential applications in solar cells and thermal photovoltaics.

**Keywords**AlN<sub>x</sub>O<sub>y</sub>

Electrical and optical properties

# ELECTRICAL AND OPTICAL PROPERTIES of $\text{Al}_x\text{O}_y$ THIN FILMS DEPOSITED by REACTIVE DC MAGNETRON SPUTTERING

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In this work a set of films of  $\text{Al}_x\text{O}_y$  and two sets of the correspondent binary systems,  $\text{AlN}_x$  and  $\text{AlO}_y$ , were produced using reactive DC magnetron sputtering, using an aluminium target and an  $\text{Ar} + (\text{N}_2 +/\text{O}_2)$  gas mixture. The discharge characteristics (target potential) and deposition rate, chemical composition, structure, electrical and optical properties of the ternary system were compared to those of the binary systems in order to test whether the oxynitride films have a unique behaviour or are simply a transition between  $\text{AlN}_x$  and  $\text{AlO}_y$ .

## DEPOSITION TECHNIQUE

### DC magnetron sputtering

Target: Aluminium, 99.5 % purity  
Substrates: Glass, Silicon <100>  
Substrate temperature before plasma: 373 K  
Partial pressure of Argon: 0.3 Pa  
Reactive gases:  $\text{N}_2$ ,  $\text{O}_2$  and  $\text{N}_2+\text{O}_2$  (17:3)  
Rotating substrates: 9 rpm.  
Bias: GND  
Target current density: 75 A/m<sup>2</sup>  
Discharge parameters monitored by a Data Acquisitionary Switch unit Agilent 4970A



## DEPOSITION CHARACTERISTICS

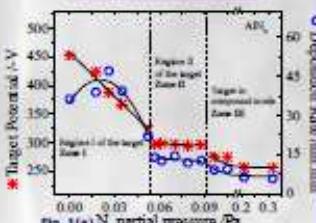


Fig. 1(a)  $\text{N}_2$  partial pressure (Pa)

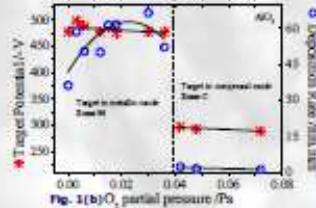


Fig. 1(b)  $\text{O}_2$  partial pressure (Pa)

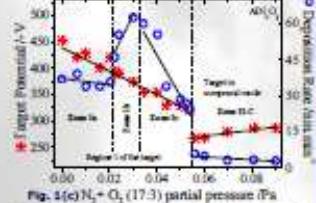


Fig. 1(c)  $\text{N}_2 + \text{O}_2$  (17:3) partial pressure (Pa)

The Target Potential is clearly influenced by the gas mixture partial pressure. In the  $\text{AlO}_y$  system the transition from a clean to a poisoned target is very abrupt, while in the  $\text{AlN}_x$  and  $\text{Al}_x\text{O}_y$  systems the transition is smoother.

The deposition rate (thickness/deposition time) has also distinct variations in each system:

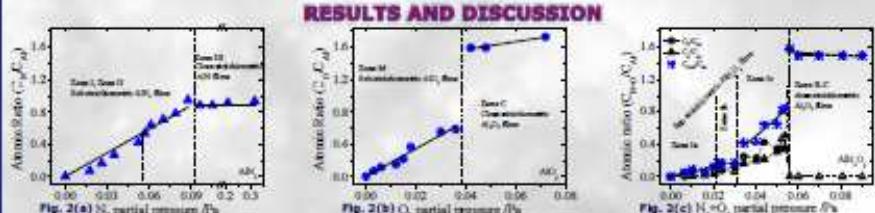


Fig. 2 Atomic ratio of (a)  $\text{AlN}_x$ , (b)  $\text{AlO}_y$  and (c)  $\text{Al}_x\text{O}_y$  films.

The transition from sub-stoichiometric towards close-stoichiometric films is relatively smooth in  $\text{AlN}_x$ , very abrupt in  $\text{AlO}_y$ , and different tendencies can be found in  $\text{Al}_x\text{O}_y$  system according to the particular zones identified.

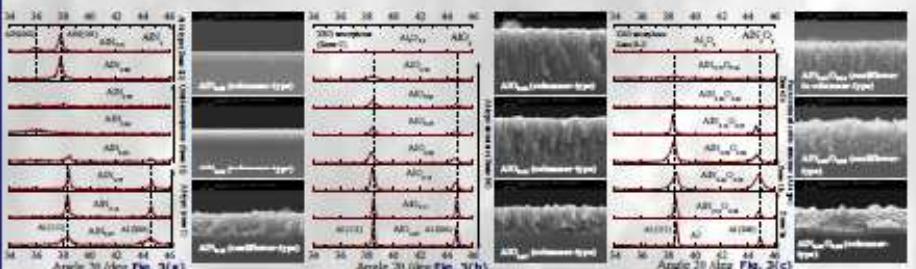


Fig. 3 XRD and representative SEM cross sections of (a)  $\text{AlN}_x$ , (b)  $\text{AlO}_y$  and (c)  $\text{Al}_x\text{O}_y$  systems.

In the  $\text{AlN}_x$  system an Al-type structure is observed for low stoichiometries (zone I), then the films become XRD amorphous (zone II) and finally crystallize in a hexagonal (wurtzite) structure (Al-type structure). The sub-stoichiometric  $\text{AlO}_y$  films (Zone M) are also composed of Al crystals, becoming XRD amorphous when close-stoichiometric  $\text{AlO}_y$  films are formed (Zone C). In the  $\text{Al}_x\text{O}_y$  system the Al-type structure is maintained in the sub-stoichiometric films (Zone Ia, Ib), becoming amorphous in zone Ic, ending up completely amorphous in zone II-C (again close-stoichiometric  $\text{AlO}_y$  films).

A non-columnar growth was found in some films with Al-type structure. These films, with cauliflower-like growth, are porous, which may explain the high deposition rates observed in some films.

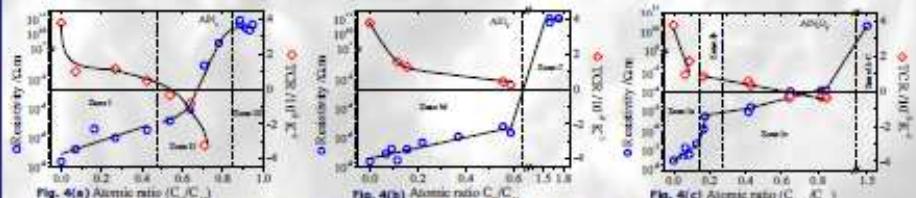


Fig. 4 Electrical resistivity and temperature coefficient of resistance (TCR) of (a)  $\text{AlN}_x$ , (b)  $\text{AlO}_y$  and (c)  $\text{Al}_x\text{O}_y$  systems.

The electrical resistivity gradually increases 3-4 orders of magnitude in the films with Al-type structure. It increases further with the rise of the atomic ratio towards semi-conductor and insulator-type resistivities.

The TCR, measured for the high conductive samples, decreases with the increase of the atomic ratio and can even be negative in the systems with nitrogen,  $\text{AlN}_x$  and  $\text{Al}_x\text{O}_y$ .

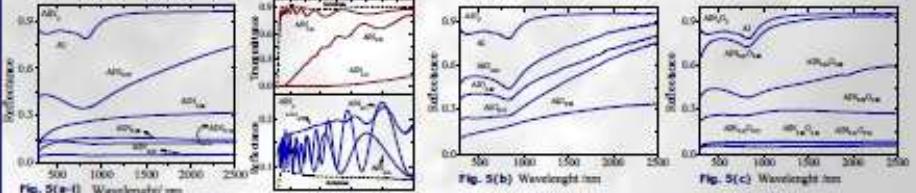


Fig. 5 Reflectance and transmittance of (a-i)  $\text{AlN}_x$  system and reflectance of (b)  $\text{AlO}_y$  and (c)  $\text{Al}_x\text{O}_y$  systems.

The films indexed to zone I of the  $\text{AlN}_x$  system are opaque and the typical interband absorption of aluminum at ~800 nm can be observed. The reflectance drops from the typical Al profile towards very low values. In zone II, as the atomic ratio increases, the reflectance increases again and interference fringes can be observed for higher ratios. The films become semi-transparent, ending up with a very high transmittance in zone III. In  $\text{AlO}_y$  system, the films indexed to zone M are opaque with a marked decrease of the reflectance, becoming transparent in zone C. In the  $\text{Al}_x\text{O}_y$  system the reflectance also drops to low values as the atomic ratio increases and also a flat reflectance, as low as 5%, can be observed in the films indexed to zone IIc.

## CONCLUSIONS

The composition and structure of the films are strongly dependent of the target condition and deposition characteristics [1]. It was found that the three systems have distinct electrical and optical responses opening the possibility to tailor the properties of the  $\text{Al}_x\text{O}_y$  from those of the correspondent binary systems, according to the application envisaged. The properties of the ternary system can be explained assuming that the films (zone IIc) are in fact a percolation network of aluminum nanoparticles embedded in an oxynitride matrix [2]. The aluminum grains can form irregularly shaped clusters with different sizes through the matrix, inducing a broadband absorption nearly independent of the wavelength. The conductivity is also governed by the restrictions between grains that can be in contact or separated by insulating barriers (oxide/nitride and/or voids). The barrier component of the films resistance has a negative dependence on the temperature and thus explaining the negative TCR for some films.

[1] J. Borges, F. Vaz, L. Marques, Applied Surface Science 257/5 (2010) 1475.

[2] J. Borges, N. Martin, N.P. Barreiras, E. Alves, D. Eyidi, M.F. Beaufort, J.P. Rivière, F. Vaz, L. Marques, Thin Solid Films 520/21 6709.

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